

L Number	Hits	Search Text	DB	Time stamp
-	4028	(qfps qfp (quad adj flat adj packs) (quad adj flat adj package))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/12/10 10:02
-	304	ir near1 voltage near1 drop\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/12/10 10:04
-	10608	(wre wiring) with parallel	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/12/10 10:04
-	0	((ir near1 voltage near1 drop\$4) and ((wre wiring) with parallel))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/12/10 10:04
-	98123	voltage near1 drop\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/12/10 10:05
-	600	((wre wiring) with parallel) and (voltage near1 drop\$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/12/10 10:05
-	3	((qfps qfp (quad adj flat adj packs) (quad adj flat adj package))) and (((wre wiring) with parallel) and (voltage near1 drop\$4))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/12/10 10:05
-	72	((wre wiring) with parallel) and (voltage near1 drop\$4)) and ((bonding bond) near pad)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/12/10 10:06
-	69	((wre wiring) with parallel) and (voltage near1 drop\$4)) and ((bonding bond) near pad)) and (die chip)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/12/10 10:10
-	31	(die chip (integrated adj circuit)) same (((two pair) near1 ((bond bonding) adj pad)) near2 (wire wiring))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/12/10 10:20
-	3860	(die chip (integrated adj circuit)) same (((bond bonding) adj pad) near2 (wire wiring))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/12/10 10:22
-	6	"6169331"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/12/10 10:24
-	11	"5905639"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/12/10 10:25
-	9	"6097098"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/12/10 10:25
-	11	"5838072"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/12/10 10:26
-	11	"6091140"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/12/10 10:38
-	11	"5883427"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/12/10 10:38

-	9	"6144102"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/12/10 10:38
-	8	"6291884"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/12/10 10:39
-	4	"6211461"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/12/10 10:39
-	8	"5793104"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/12/10 10:39
-	10	"5864174"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/12/10 10:39
-	14	"5412247"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/12/10 10:39
-	12	"6300685"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/12/10 10:39
-	2	"6218728"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/12/10 10:40
-	114	("6169331" "5905639" "6097098" "5838072" "6091140" "5883427" "6144102" "6291884" "6211461" "5793104" "5864174" "5412247" "6300685" "6218728") not (((wre wiring) with parallel) and (voltage near1 drop\$4)) and ((bonding bond) near pad)) not ((die chip (integrated adj circuit)) same (((two pair) near1 ((bond bonding) adj pad)) near2 (wire wiring)))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/12/10 10:40
-	114	"6169331" "5905639" "6097098" "5838072" "6091140" "5883427" "6144102" "6291884" "6211461" "5793104" "5864174" "5412247" "6300685" "6218728"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/12/10 10:41
-	0	6472764.URPN.	USPAT	2002/12/10 10:46
-	17	("4213141"   "4403240"   "5043943"   "5303180"   "5353250"   "5354955"   "5399904"   "5455460"   "5598967"   "5612575"   "5682105"   "5763298"   "5838072"   "5880596"   "5989939"   "6097098"   "6194774").PN.	USPAT	2002/12/10 10:46
-	4	6194774.URPN.	USPAT	2002/12/10 10:53
-	27	("3614554"   "4446445"   "5024966"   "5173672"   "5221984"   "5321299"   "5376902"   "5378869"   "5394008"   "5519233"   "5572180"   "5576680"   "5639989"   "5710068"   "5736749"   "5744869"   "5767563"   "5793096"   "5849355"   "5877667"   "5880517"   "5886393"   "5912997"   "5920067"   "5929636"   "5966063"   "5973567").PN.	USPAT	2002/12/10 10:54
-	6	5989939.URPN.	USPAT	2002/12/10 11:46
-	8	("4764848"   "5148265"   "5148266"   "5455390"   "5476211"   "5801446"   "5806181"   "5829128").PN.	USPAT	2002/12/10 11:46

-	8	("5170312"   "5172471"   "5276352"   "5304737"   "5473196"   "5587607"   "5686764"   "5723906").PN.	USPAT	2002/12/10 11:49
-	17	5473196.URPN.	USPAT	2002/12/10 11:53
-	103	("3851221"   "4567643"   "4730232"   "4763188"   "4883773"   "4982265"   "4996587"   "5012323"   "5025306"   "5040052"   "5104820"   "5117282"   "5138438"   "5140404"   "5148265"   "5162260"   "5165067"   "5198888"   "5229647"   "5258330"   "5291061"   "5323060"   "5334875"   "5343366"   "5347429"   "5384689"   "5422435"   "5426072"   "5426563"   "5432318"   "5432729"   "5455740"   "5463253"   "5473196"   "5477611"   "5479318"   "5481134"   "5493476"   "5495394"   "5495398"   "5502289"   "5514907"   "5519936"   "5533256"   "5536909"   "5541812"   "5552963"   "5569625"   "5581498"   "5586009"   "5587341"   "5605592"   "5608262"   "5614766"   "5633785"   "5637536"   "5637912"   "5650593"   "5654220"   "5682062"   "5684330"   "5689135"   "5696031"   "5715147"   "5716221"   "5721452"   "5739581"   "5744284"   "5753974"   "5766987"   "5777391"   "5783870"   "5793108"   "5798014"   "5815372"   "5824177"   "5847932"   "5858815"   "5861666"   "5863813"   "5866949"   "5872025"   "5885849"   "5886412"   "5917242"   "5950070"   "5952611"   "5973403"   "5989982"   "6005778"   "6025251"   "6028354"   "RE36613"   "6043109"   "6051886"   "6057598"   "6072154"   "6072243"   "6080264"   "6184463"   "6204091"   "6214641"   "6235554").PN.	USPAT	2002/12/10 11:55
-	1	"5239447".PN.	USPAT	2002/12/10 12:05
-	17	5473196.URPN.	USPAT	2002/12/10 12:05
-	8	("5170312"   "5172471"   "5276352"   "5304737"   "5473196"   "5587607"   "5686764"   "5723906").PN.	USPAT	2002/12/10 12:08
-	1	"3688132".PN.	USPAT	2002/12/10 12:14
-	8	("5394009"   "5627408"   "5777391"   "5793104"   "5864174"   "5956233"   "5976916"   "6013948").PN.	USPAT	2002/12/10 12:19
-	5	("4897918"   "5388327"   "5490324"   "5594275"   "5990565").PN.	USPAT	2002/12/10 12:21
-	1	6211461.URPN.	USPAT	2002/12/10 12:21
-	2	6169331.URPN.	USPAT	2002/12/10 12:23

-	43	("4080485"   "4241360"   "4359754"   "4403240"   "4750666"   "4984065"   "5036015"   "5058798"   "5081520"   "5235212"   "5298793"   "5343064"   "5355004"   "5359227"   "5367195"   "5371654"   "5384487"   "5492863"   "5539251"   "5550083"   "5559428"   "5587607"   "5650914"   "5677574"   "5681647"   "5712695"   "5723906"   "5804876"   "5808354"   "5817030"   "5818564"   "5821624"   "5828116"   "5838072"   "5854513"   "5879530"   "5909055"   "5923091"   "6008533"   "6008542"   "6013944"   "6025651"   "6028354").PN.	USPAT	2002/12/10 12:23
-	7	5714800.URPN.	USPAT	2002/12/10 12:34
-	15	("5081563"   "5126813"   "5148265"   "5148266"   "5227232"   "5258330"   "5315486"   "5319241"   "5381047"   "5402318"   "5412247"   "5414298"   "5463246"   "5491362"   "5528075").PN.	USPAT	2002/12/10 12:35
-	34	(US-6489667-\$ or US-6479887-\$ or US-6472764-\$ or US-6194774-\$ or US-6424223-\$ or US-5767563-\$ or US-5519233-\$ or US-5376902-\$ or US-6097098-\$ or US-5989939-\$ or US-5148265-\$ or US-5473196-\$ or US-5973403-\$ or US-5950070-\$ or US-5696031-\$ or US-5495398-\$ or US-5258330-\$ or US-5838072-\$ or US-6462407-\$ or US-6445077-\$ or US-6300685-\$ or US-6291884-\$ or US-6211461-\$ or US-6169331-\$ or US-6476506-\$ or US-6008533-\$).did. or (US-5828116-\$ or US-4403240-\$ or US-4359754-\$ or US-6091140-\$ or US-5905639-\$ or US-5883427-\$ or US-5714800-\$).did. or (JP-2000151223-\$).did.	USPAT; DERWENT	2002/12/10 12:40
-	4	("6169331" "5905639" "6097098" "5838072" "6091140" "5883427" "6144102" "6291884" "6211461" "5793104" "5864174" "5412247" "6300685" "6218728") and (stitch adj bond)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/12/10 13:08
-	10	("6169331" "5905639" "6097098" "5838072" "6091140" "5883427" "6144102" "6291884" "6211461" "5793104" "5864174" "5412247" "6300685" "6218728") and ((ball adj bond)(stitch adj bond))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/12/10 13:18
-	14	("5359227"   "5468999"   "5691568"   "5796171"   "5801450"   "5962926"   "6121690"   "6148505"   "6160313"   "6169331"   "6215182"   "6291898"   "6297078"   "6307271"   "2001/0017411"   "2002/0011654"   "2002/0024146").PN.	USPAT	2002/12/10 13:14
-	238	((die chip (integrated adj circuit)) same (((bond bonding) adj pad) near2 (wire wiring))) and ((ball adj bond)(stitch adj bond))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/11/14 08:38
-	104	((die chip (integrated adj circuit)) same (((bond bonding) adj pad) near2 (wire wiring))) and (((ball adj bond)(stitch adj bond)) near3 (ball pad))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/11/14 08:39
-	22	((die chip (integrated adj circuit)) same (((bond bonding) adj pad) near2 (wire wiring))) and ((ball adj bond) near3 (ball pad)) and ((stitch adj bond) near3 (ball pad))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/11/14 08:40

-	15	((die chip (integrated adj circuit)) same ((bond bonding) adj pad) near2 (wire wiring))) and ((ball adj bond) near2 (ball pad)) and ((stitch adj bond) near2 (ball pad))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/12/10 13:30
-	2	5989939.pn. and (wire wiring)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/12/11 09:59
-	0	5989939.pn. and (gold copper aluminum)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/12/11 10:02
-	1	5989939.pn. and trace	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/12/11 10:23
-	6	"6169331"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/12/11 10:28
-	3	"6169331" and ((stitch adj bond) (ball adj bond))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/12/11 10:29
-	8	("4393392"   "4720915"   "4751482"   "5006673"   "5371405"   "5616952"   "5677570"   "5789816").PN.	USPAT	2003/06/15 12:05
-	10	5838072.URPN.	USPAT	2003/06/15 12:06
-	0	6351040.URPN.	USPAT	2003/06/15 12:14
-	17	("4213141"   "4403240"   "5043943"   "5303180"   "5353250"   "5354955"   "5399904"   "5455460"   "5598967"   "5612575"   "5682105"   "5763298"   "5838072"   "5880596"   "5989939"   "6097098"   "6194774").PN.	USPAT	2003/06/15 12:14
-	0	6348400.URPN.	USPAT	2003/06/15 12:19
-	17	("4213141"   "4403240"   "5043943"   "5303180"   "5353250"   "5354955"   "5399904"   "5455460"   "5598967"   "5612575"   "5682105"   "5763298"   "5838072"   "5880596"   "5989939"   "6097098"   "6194774").PN.	USPAT	2003/06/15 12:19
-	288	((die chip (integrated adj circuit)) same ((bond bonding) adj pad) near2 (wire wiring))) and ((ball adj bond) (stitch adj bond))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/11/14 08:38
-	132	((die chip (integrated adj circuit)) same ((bond bonding) adj pad) near2 (wire wiring))) and ((ball adj bond) (stitch adj bond)) near3 (ball pad))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/11/14 08:39
-	38	((die chip (integrated adj circuit)) same ((bond bonding) adj pad) near2 (wire wiring))) and ((ball adj bond) (stitch adj bond))) and ((stitch adj bond) near3 (ball pad))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/11/14 08:40